

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT

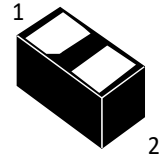


PLED

Product data sheet

FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Extremely small surface mounting type.(DFN0603)
- Low IR.
- High reliability.



APPLICATIONS

- Low current rectification

0201

MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
DC Reverse Voltage	VR	30	V
Mean Rectifying Current	IO	100	mA
Peak Forward Surge Current	IFSM	2	A

THERMAL CHARACTERISTICS

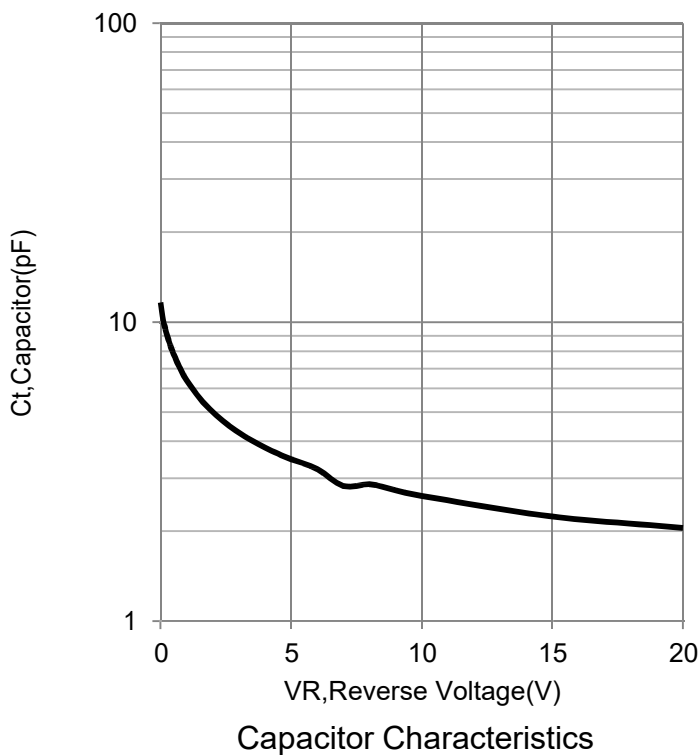
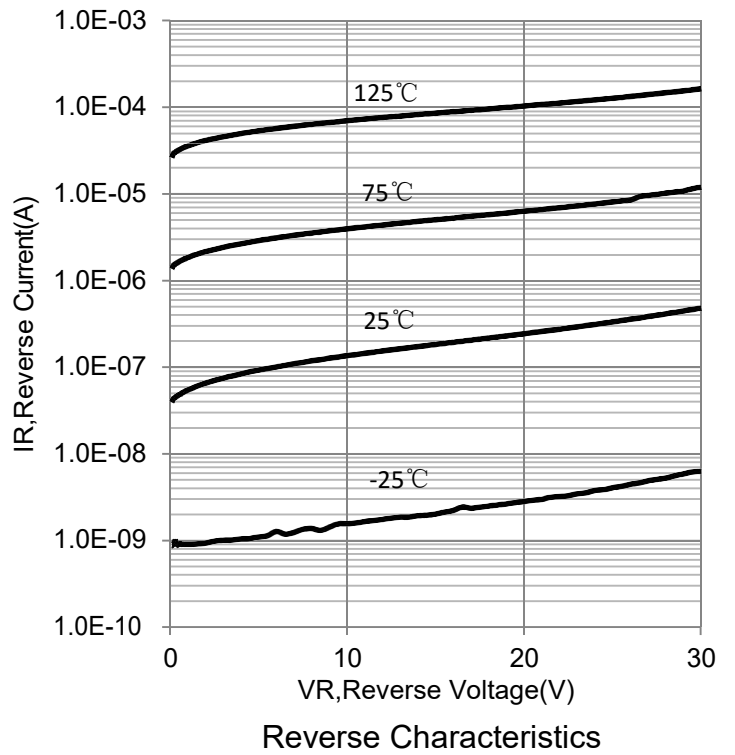
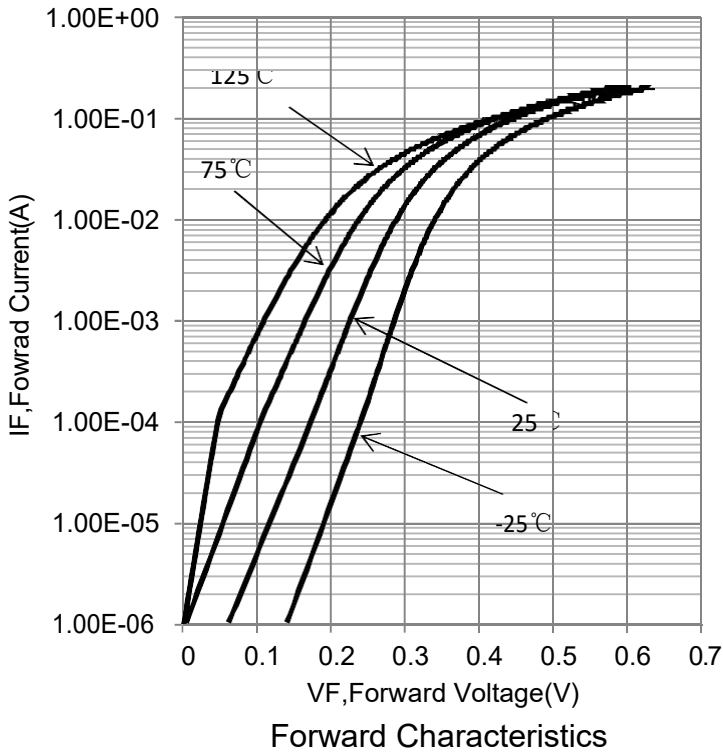
Parameter	Symbol	Limits	Unit
Total Device Dissipation, FR-5 Board (Note 1) @ TA = 25°C Derate above 25°C	PD	200 1.58	mW mW/°C
Thermal Resistance, Junction-to-Ambient(Note 1)	RθJA	500	°C/W
Junction Temperature	TJ	125	°C
Storage Temperature Range	Tstg	-40~+150	°C
Operating Temperature Range	Top	-40~+125	°C

1. FR-5 = 1.0×0.75×0.062 in.

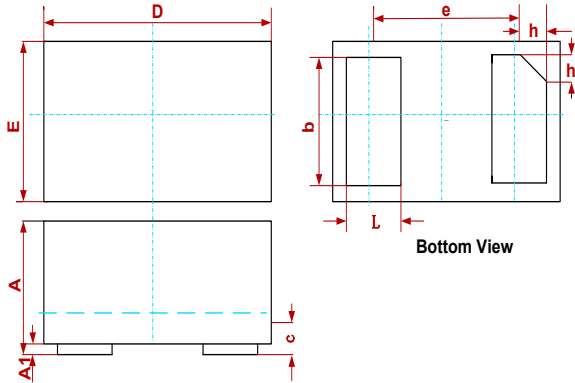
ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Reverse Voltage Leakage Current (VR = 10Vdc) (VR = 30Vdc)	IR	- -	- -	0.35 0.7	μA
Diode Capacitance (VR = 0V , f = 1.0 MHz)	CT	-	8.2	-	pF
Forward Voltage (IF = 100 mAdc) (IF = 10 mAdc)	VF	- -	- -	0.62 0.5	V

ELECTRICAL CHARACTERISTICS CURVES

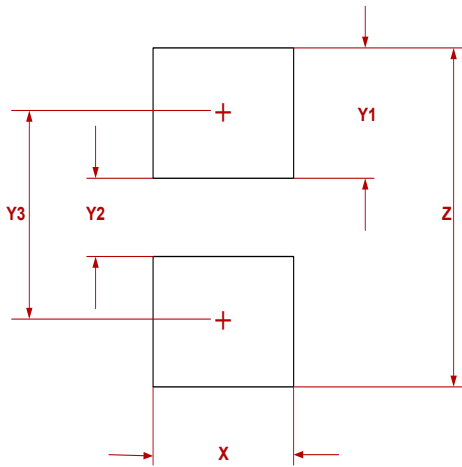


PACKAGE MECHANICAL DATA



SYM	DIMENSIONS		
	MILLIMETERS		
	MIN	NOM	MAX
A	0.230		0.330
A1	0.000	0.020	0.050
b	0.215	0.245	0.275
c	0.120	0.150	0.180
D	0.550	0.600	0.650
e	0.355 BSC		
E	0.250	0.300	0.350
L	0.160	0.190	0.220
h	0.079 BSC		

Suggested Pad Layout



SYM	DIMENSIONS	
	MILLIMETERS	INCHES
X	0.30	0.012
Y1	0.25	0.010
Y2	0.15	0.006
Y3	0.40	0.016
Z	0.65	0.026

REEL SPECIFICATION

P/N	PKG	QTY
BAT30F4-MS	0201	10000

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